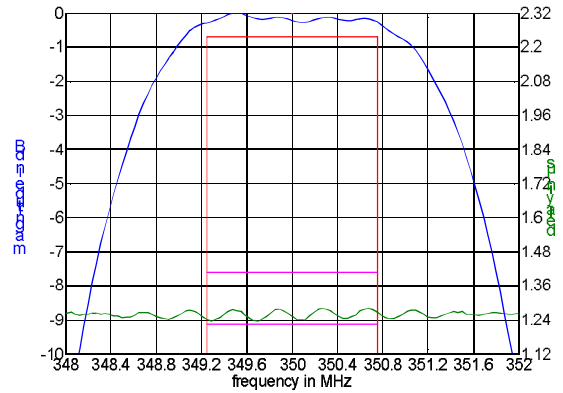
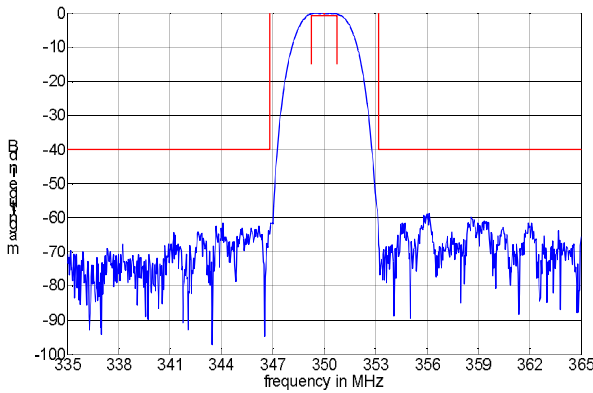


VI TELEFILTER

Filter specification

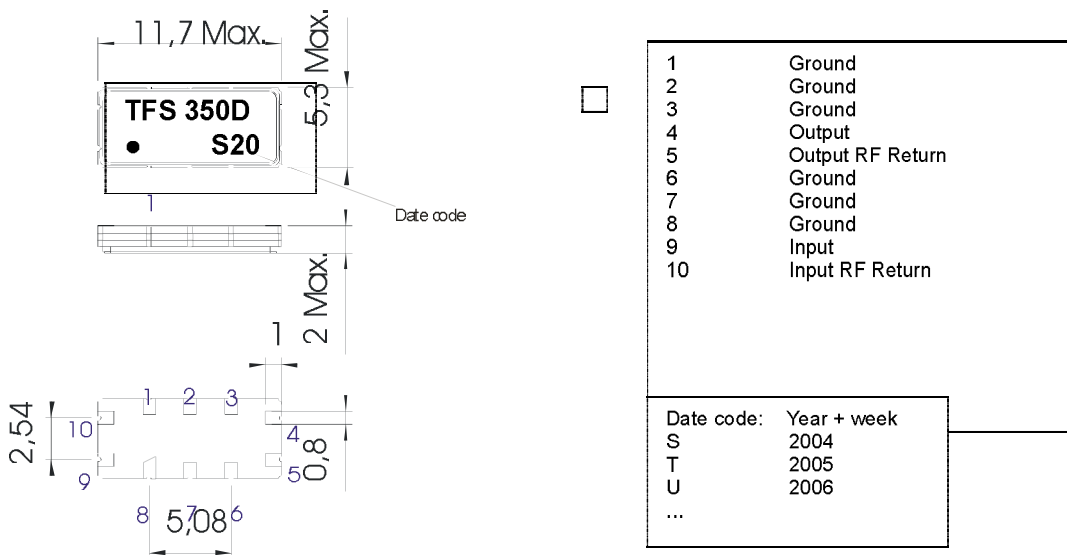
TFS 350D

Filter characteristic

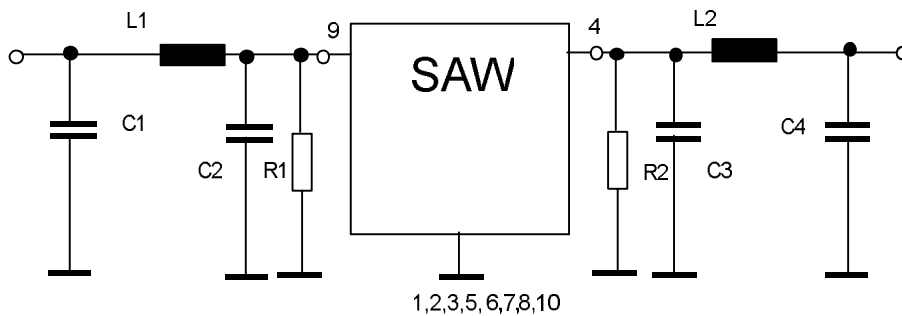


Construction and pin connection

(All dimensions in mm)



50 Ω Test circuit



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Filter specification

TFS 350D

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Stability Characteristics

After the following tests the filter shall meet the whole specification:

1. Shock: 500g, 18 ms, half sine wave, 3 shocks each plane;
DIN IEC 68 T2 - 27
2. Vibration: 10 Hz to 500 Hz, 0,35 mm or 5g respectively, 1 octave per min, 10 cycles per plan, 3 plans;
DIN IEC 68 T2 - 6
3. Change of temperature: -55 °C to 125 °C / 30 min. each / 10 cycles
DIN IEC 68 part 2 – 14 Test N
4. Resistance to solder heat (reflow): reflow possible: twice max.;
for temperature conditions, please refer to the attached "Air reflow temperature conditions" on page 4;

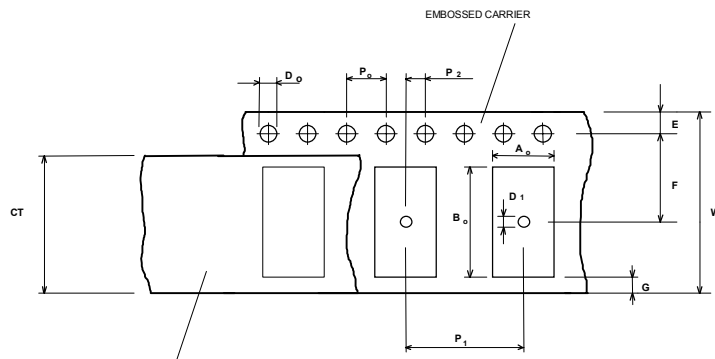
Packing

Tape & Reel: DIN IEC 286 – 3, with exception of value for N and minimum bending radius;
tape type II, embossed carrier tape with top cover tape on the upper side;

max. pieces of filters per reel:	3000
reel of empty components at start:	min 300 mm
reel of empty components at start including leader:	min 500 mm
trailer	min 300 mm

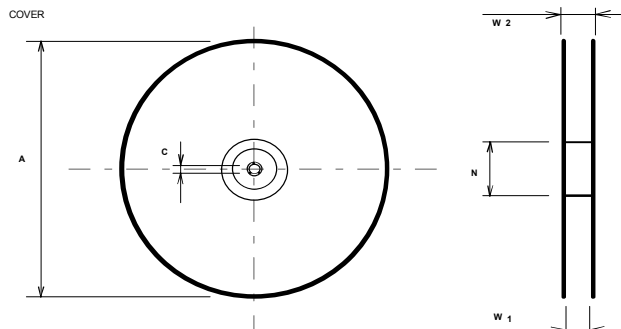
Tape (all dimensions in mm)

- W : 24 ± 0,3
- Po : 4 ± 0,1
- Do : 1,5 ± 0,1
- E : 1,75 ± 0,1
- F : 7,5 ± 0,1
- G (min) : 0,6
- P2 : 2 ± 0,1
- P1 : 8 ± 0,1
- D1(min) : 1,5
- Ao : 5,6 ± 0,1
- Bo : 11,8 ± 0,
- CT : 21,5 ± 0,1



Reel (all dimensions in mm):

- A : 330
- W1 : 24,4 +2
- W2 (max): 30,4
- N (min) : 60
- C : 13 +0,5/-0,2



The minimum bending radius is 45 mm. The mounting surface of the filters faces the bottom side of the embossed carrier tape. Markings on the filters can be read if the upper side of the carrier tape is regarded with the sprocket holes on its right.

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Air reflow temperature conditions

1st and 2nd air reflow profile

Name:	pre-heating periods	main-heating periods	peak temperature
Temperature:	150 °C – 170 °C	over 200 °C	255 °C ± 5 °C
Time:	60 sec. – 90 sec.	20 sec. – 25 sec.	

Chip-mount air reflow profile

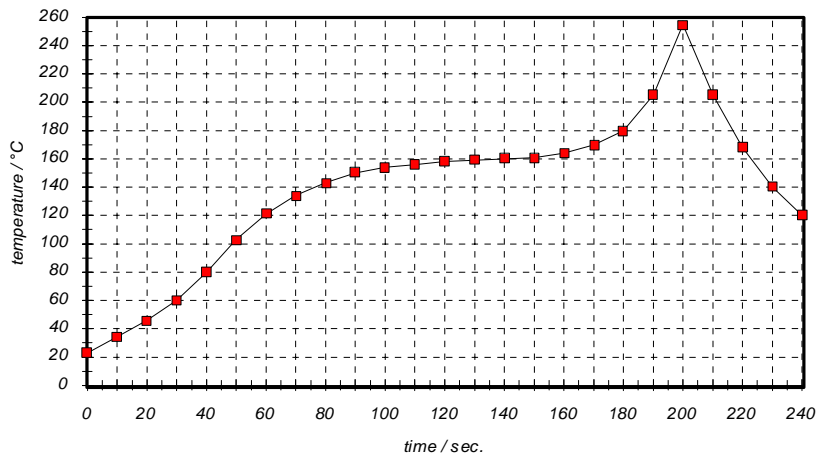


Table for temperature vs. Time during the air reflow process

Tolerance of temperatures: ± 5 °C

time / sec.	Temperature / °C	time / sec.	Temperature / °C
0	23	140	160
10	34	150	161
20	46	160	164
30	60	170	170
40	80	180	180
50	103	190	205
60	121	195	230
70	134	200	255
80	143	205	230
90	150	210	205
100	154	215	180
110	156	220	165
120	158	230	140
130	159	240	120

VI TELEFILTER**Filter specification****TFS 350D****5/5****History**

Version	Reason of Changes	Name	Date
1.0	generation of specification according to customer requirements	Pfeiffer	28.01.2002
1.1	typical value for return loss and extended storage temperature range added	Steiner	11.02.2002
1.2	typical values added terminating impedance added changing pinning 'output rf return'	Pfeiffer	24.05.2002
1.3	package (pin 1 marker) modified filter characteristic added	Pfeiffer	13.05.2004

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